

IN THE CLAIMS

Claim 25 is amended as indicated below. Claims 27 and 29-32 are cancelled.

1. (Previously Presented) An integrated circuit package comprising:
a molded plastic body;
a plurality of plastic posts arranged in a checkerboard pattern, each said post extending integrally from said body;
a plurality of electrically separate metal terminals coating a sidewall of at least one of said posts;
a plurality of electrically conductive paths each electrically coupled to at least one of said metal terminals; and
an integrated circuit including a plurality of bond pads, said integrated circuit mounted on said body and electrically coupled to at least some of said paths through said bond pads.
2. (Original) The integrated circuit package of Claim 1, wherein a total number of said posts is less than a total number of said bond pads.
3. (Previously Presented) The integrated circuit package of Claim 1, wherein said posts are adapted to engage posts of another structure arranged in a reciprocal checkerboard pattern.
4. (Original) The integrated circuit package of Claim 1, wherein a shape of at least some of said posts comprises a cylinder.
- 5-7. (Withdrawn)
8. (Original) The integrated circuit package of Claim 1, further comprising a plurality of bond wires each electrically coupled between said bond pads and at least some of said paths.
9. (Original) The integrated circuit package of Claim 1, further comprising an encapsulant material covering at least a part of said integrated circuit.

10. (Withdrawn)

11-23. (Cancelled)

24. (Withdrawn)

25. (Presently Amended) An integrated circuit package comprising:
a plastic body with a plurality of plastic posts each extending integrally from said body, each said post having a plurality of separate metal layers coated on a sidewall of the post, wherein said posts are arranged in a checkerboard pattern;
metal traces overlying the plastic body;
metal vias extending through the plastic body, with each via being electrically coupled between at least one said trace and one said metal layer; and
an integrated circuit coupled to said body, wherein the integrated circuit is electrically coupled to at least two of the separate metal layers of each of at least two of the posts through some of said metal traces and said vias.

26. (Previously Presented) The integrated circuit package of Claim 25, wherein the integrated circuit includes a plurality of bond pads each electrically coupled to one of said metal layers, and a total number of said posts is less than a total number of said bond pads.

27. (Cancelled)

28. (Previously Presented) The integrated circuit package of Claim 25, wherein a shape of at least some of said posts comprises a cylinder.

29-32. (Cancelled)